

Product Change Notification Number: GC183122**Date 25 September 2018****Title: Migration of PC5674F to TSMC wafer fab and Copper Wirebond****Product Identification:**

PC5674FF3MZP3

Reason for Change:

<input type="checkbox"/> Design	<input type="checkbox"/> Processing	<input type="checkbox"/> Logistics
<input type="checkbox"/> Other	<input checked="" type="checkbox"/> Manufacturing Location	<input checked="" type="checkbox"/> Material
	<input type="checkbox"/> Quality/Reliability	

Change Description:

In order to rationalize its procurements, Teledyne e2v aligns with NXP announcement ref. 16151.

- The primary NXP wafer manufacturing site transfer to TSMC14 will improve ability to meet customer demand.
- The transfer from Gold to Copper wire is required to standardize manufacturing flows and mitigate against raw material cost increases

Anticipated Impact of Product Change (Form, Fit, Function):

No changes will be seen in form, fit, or function.

Identification Method to Distinguish Change:

P/N and marking will show the code name 'K4' instead of previous 'F3'. It will be PC5674FK4MZP3. Datasheets will be updated accordingly.

Qualification Data:

applicable

<input type="checkbox"/> available	<input checked="" type="checkbox"/> will be available in MARCH-2019	<input checked="" type="checkbox"/> not
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Samples:

<input type="checkbox"/> prototypes available	<input type="checkbox"/> will be available	<input checked="" type="checkbox"/> not applicable
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Quantifiable Impact on Quality & Reliability: *None expected.***Implementation Date*:***Immediate*

*The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, e2v semiconductors will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.

Teledyne e2v semiconductors contact:

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Please contact your local Teledyne-e2v sales representative for any commercial inquiry.

APPROVAL by TRB

Teledyne e2v semiconductors will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the contact e-mail addresses indicated above.

A Teledyne e2v semiconductor assumes no responsibility for any errors that may appear in this document.

The supply of products will be subject to Teledyne e2v general terms and conditions of sale or any specific contractual terms agreed between the parties.

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